Automated Test Management
- Automated Thermal Management (ATM™) minimizes thermal drift and reduces wafer and die soak times, ensuring shortest time to reach thermal equilibrium after every thermal step
- Automated re-alignment capability compensates for thermal drift after every temperature change
- Reliable and repeatable contact on small pads down to 30 µm and microbumps

Advanced EMI/RFI Shielding
- Ensures highly-accurate low-leakage and low-noise measurement results
- Minimizes settling times for efficient measurements, without compromising accuracy over full thermal range

Integrated Shielding Solution
- Chuck enclosure ensures moisture-free, light-tight and EMI-shielded measurements
- Eliminates the need for dark box, making over-temperature measurements easy
- Top-side shielding provided by TopHat™ or optional top chambers

Mechanical Accuracy
- Stage accuracy and stability ensure precise and repeatable small-pad and fine-pitch probing
- Ideal for testing modeling and reliability structures in the kerfs and microbumps
- High-resolution probe-to-pad alignment (PTPA) for use with vertical/advanced probe cards (option)

Upgrade to Fully-Automated System (Option)
- Field upgradeable with handling unit to allow test automation out-of-cassette for higher test cell efficiency for over-night/over-weekend operation

Large Microscope Bridge
- Easy to mount measurement instruments such as parameter or noise analyzer and VNA, as close as possible to the DUT
- Minimizes signal path to eliminate parasitic effects, achieving high measurement accuracy and dynamics

Velox™ User Interface
- Intuitive GUI for efficient system utilization by novice and expert users
- Analog joystick for precise, sub-micron positioning
- Easy integration with instrument, testers, and test and measurement software for fast data collection
- Automated wafer alignment and auto XY and theta correction for sub-micron slapping

Quick Access to Auxiliary Chucks
- Two patented auxiliary chucks for high calibration accuracy for RF/mmW measurements at frequencies up to 110 GHz
- Three sites for advanced cleaning procedures and contact verification

Probing Over Wide Thermal Range
- -60˚C to 300˚C systems available for characterization and modeling
- Thermally optimized platen, shielding solution and ultra-flat wafer chucks ensure stable and repeatable measurements

Safe Wafer Loading and Unloading
- Full wafer access via locking roll-out stage
- Easily handles 200/300 mm wafers and smaller, as well as single die and wafer fractions

Built-in Vibration-Isolation System
- Eliminates vibration from external sources, such as acoustic and architectural, enabling reliable small pad probing
- Enhances system stability and reduces damage to pads, wafers and probe tips
- Easy access from front- and back-side for fast configuration and service

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